## **INFORMATION NOTE**



## N° 027/15

## BSS670S2L H6327 - Modification of die orientation

Subject of Change: Modification of die orientation

Products affected: Type SP N° OPN Package

BSS670S2L SP000928950 BSS670S2LH6327XTSA1 PG-SOT23-3

H6327

Reason of Change: Change of die rotation to standardize wire position with other products in

PG-SOT23 packages

Die rotation

Original die orientation

90 degree rotated die

Assessment: No influence on fit, form, function and reliability

Die bonding: no influence as the die size is square Wire bonding: standardization of wire position

Time Schedule: Beginning CW 43

If you have any questions, please do not hesitate to contact your local Sales office.

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